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MEMS Material Property Test Structures

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Stress Measurement Via Wafer Curvature

- Compressively stressed film → bends a wafer into a convex shape
- Tensile stressed film → bends a wafer into a concave shape
- Can optically measure the deflection of the wafer before and after the film is deposited
- Determine the radius of curvature R , then apply:

$$\sigma = \frac{E'h^2}{6Rt}$$

σ = film stress [Pa]
 $E' = E/(1-\nu)$ = biaxial elastic modulus [Pa]
 h = substrate thickness [m]
 t = film thickness
 R = substrate radius of curvature [m]

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MEMS Stress Test Structure

- Simple Approach:** use a clamped-clamped beam
 - Compressive stress causes buckling
 - Arrays with increasing length are used to determine the critical buckling load, where

$$\sigma_{critical} = -\frac{\pi^2 E h^2}{3 L^2}$$

E = Young's modulus [Pa]
 $I = (1/12)Wh^3$ = moment of inertia
 L, W, h indicated in the figure

⚠ **Limitation:** Only compressive stress is measurable

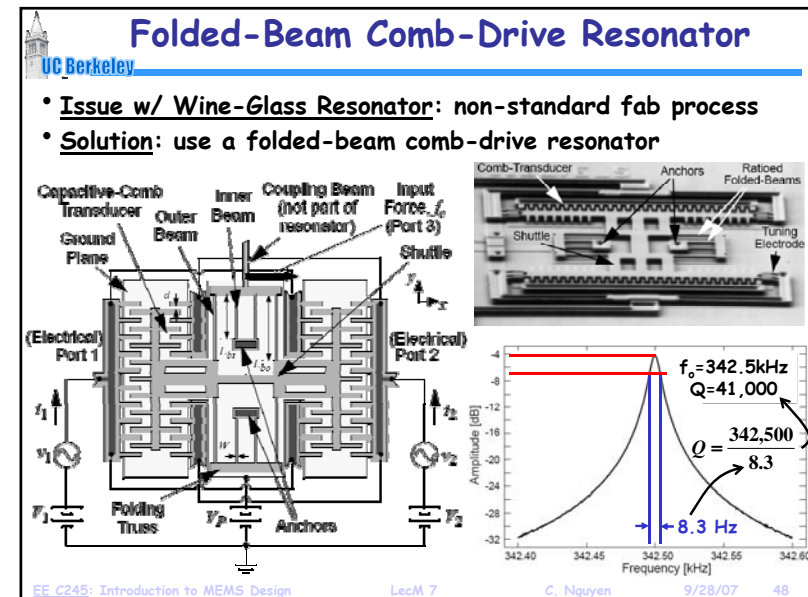
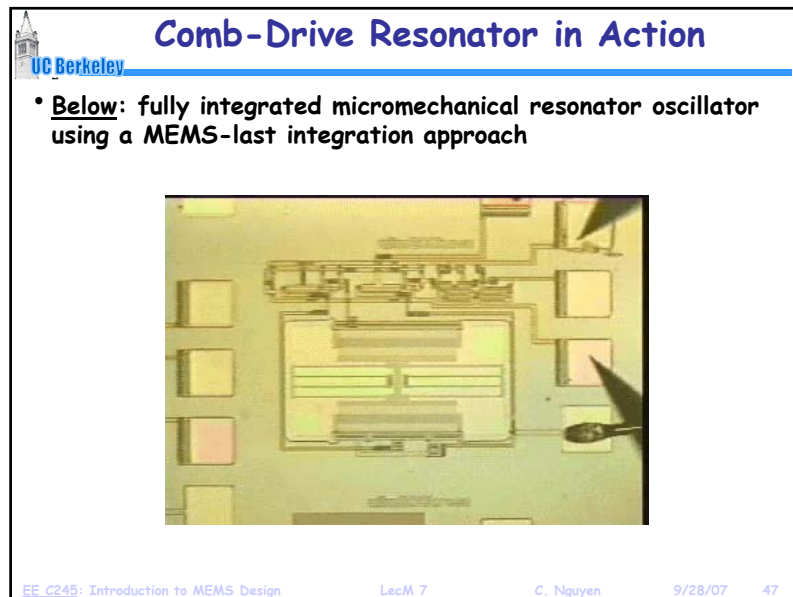
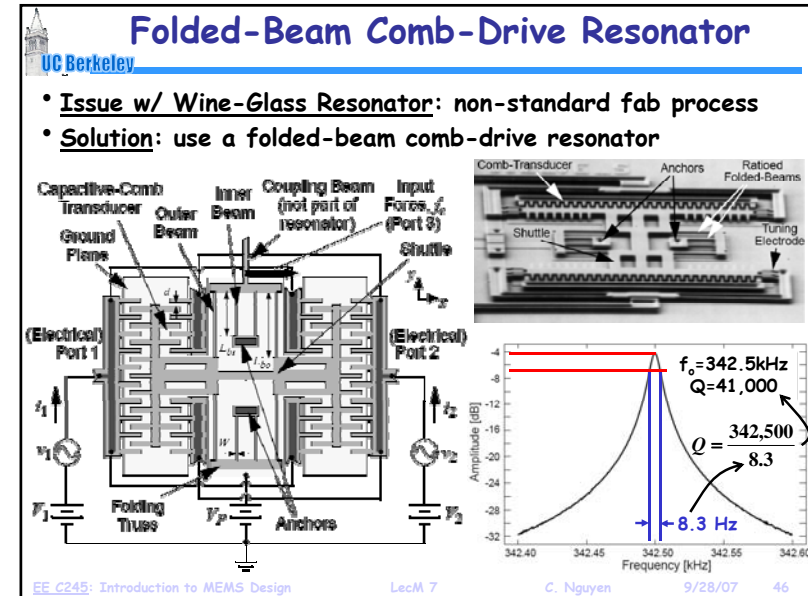
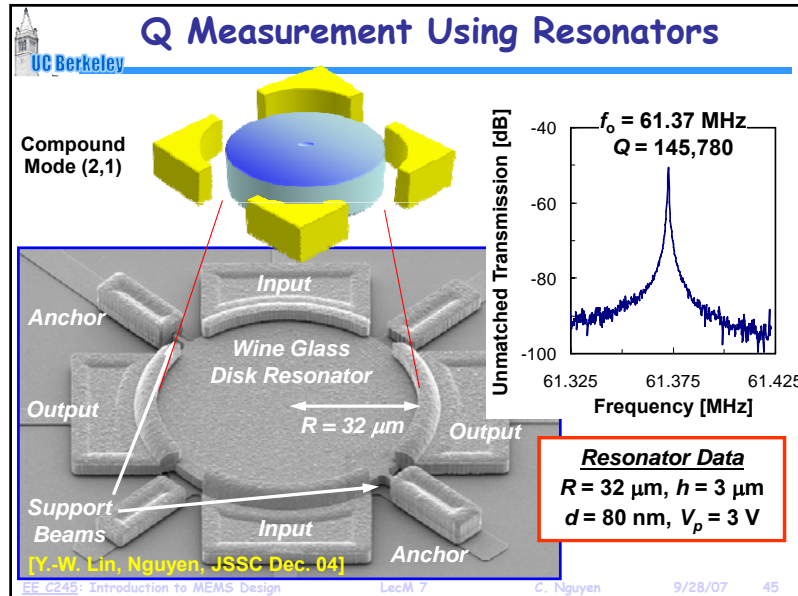
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More Effective Stress Diagnostic

- Single structure measures both compressive and tensile stress
- Expansion or contraction of test beam → deflection of pointer
- Vernier movement indicates type and magnitude of stress

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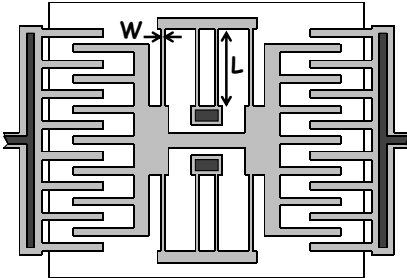
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Measurement of Young's Modulus

- Use micromechanical resonators
 - ↳ Resonance frequency depends on E
 - ↳ For a folded-beam resonator:

Resonance Frequency = $f_o = \left[\frac{4Eh(W/L)^3}{M_{eq}} \right]^{1/2}$

h = thickness



Young's modulus

Equivalent mass

- Extract E from measured frequency f_o
- Measure f_o for several resonators with varying dimensions
- Use multiple data points to remove uncertainty in some parameters

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